Applicabl	le standard										
11	Operating Temperature range Operating Humidity range Voltage Current		-55 °C         to         +105°C (Note1)         Terr           20%         to         80%         Stor           250         V         AC/DC         C-U           Rati         AWG 20 : 4 A         AWG 22 : 3A         AWG 20 : 4 A			torage emperature range		-10 °C to +60°C (Note2 40% to 70% (Note2 29.9 V AC/DC 4A			
Rating					Storage Humidity range					te2)	
					C-UL	IL ing Current					
Applicable Connector			DF62W-9S-2.2C(#	#)		Operating temperatu range		-55 °C to +75°C (Note1)			
	•		Spe	cificatio	ons						
	Item		Test method				Red	quirements	QT	AT	
Construct	tion										
General examination		Visually and by measuring instrument.			Aco	According to drawing.				Х	
Marking		Confirmed	Confirmed visually.						Х	Х	
Electric of	characteris	tics			<u> </u>				1	1	
Contact resistance		20mV MAX, 1mA (DC or 1000Hz).				30 mΩ MAX.			Х	-	
Insulation resistance		500 V DC.			100	1000 MΩ MIN.			X	-	
Voltage proof		650 V AC for 1 min.			No	No flashover or breakdown.			X	-	
Mechani	cal charac	teristics			I						
Mechanical	operation	50 times i	nsertion and extraction.		-			e: 30 mΩ MAX. < or looseness of parts.	Х	-	
Vibration		Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 10 cycles for 3 direction.				(1) No electrical discontinuity of $1 \mu$ s. (2) No damage, crack or looseness of parts.			Х	-	
Shock		490 m/s <sup>2</sup> duration of pulse 11 ms at 3 times each for 3 both axial directions.			for ①N	(1) No electrical discontinuity of $1 \mu$ s. (2) No damage, crack or looseness of parts.			Х	-	
Mating force		Measured by applicable connector.			Ins	Insertion force : 33.7 N MAX Extraction force : 1.75 N MIN			Х	-	
Lock strength		Measured	Measured by applicable connector.			30 N MIN			Х	-	
Environm	ental chara	cteristics									
Damp heat		Exposed at 40 ± 2°C , 90 to 95 %, 96 h.			10	(1)Contact resistance: 30 m $\Omega$ MAX.			Х	—	
(Steady state)		(After leaving the room temperature for 1 to 2h.)			~	(2) Insulation resistance: 500 M $\Omega$ Min.					
Danid shares of		Temperature -55°C→ +105°C				③No damage, crack or looseness of parts. ①Contact resistance: 30 mΩ MAX.					
Rapid change of temperature		Time $30 \text{min} \rightarrow 30 \text{min}$ Under 5 cycles. (The transferring time of the tank is 2 to 3 min) (After leaving the room temperature for 1 to 2h.)			<b>2</b> I	<ul> <li>②Insulation resistance: 1000 MΩ Min.</li> <li>③No damage, crack or looseness of parts.</li> </ul>			X		
Dry heat		Exposed at +105°C,96h.			21 31	<ul> <li>①Contact resistance: 30 mΩ MAX.</li> <li>②Insulation resistance: 1000 MΩ Min.</li> <li>③No damage, crack or looseness of parts.</li> </ul>			X	-	
Cold		Exposed at -55°C,96h.			<b>(2)</b>	(1) Contact resistance: 30 m $\Omega$ MAX. (2) Insulation resistance: 1000 M $\Omega$ Min. (3) No damage, crack or looseness of parts.			Х	_	
Note2: Apply		of long term s	irrent. torage for unused products befo e and humidity range is applied					ts. After before being process	ed or mo	ounted	
Cour	nt	Descripti	Description of revisions Des		Designed	signed		Checked	Da	ate	
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ST. WADA

YK. YAMAGUCHI

KI. SUGAWARA

DF62WZ-9P-2. 2DSA (50)

CL544-1050-0-50

ELC-379591-50-00

Approved Checked

Designed

Drawn

Drawing No.

Part No.

Code No.

Note

RS

Unless otherwise specified, refer to IEC 60512.

QT:Qualification Test AT:Assurance Test X:Applicable Test

Specification sheet

HIROSE ELECTRIC CO., LTD.

Specifications										
Item	Test method	Requirements	QT	AT						
Resistance to Soldering heat	<ol> <li>Automatic soldering (flow) Soldered at solder temperature,260°C for in immersion,duration,10s.</li> <li>Manual soldering Soldering iron temperature:300°C, Soldertime:3s. No strength on contact.</li> </ol>	No defomation of case of excessive looseness of the terminals.	X	_						
Solderability	Soldered at solder tempereture 245°C for in immersion,duration,5s.	A new uniform coating of solder shall cover minimum of 95% of the surface being immersed.	X	_						
Sealing	Exposed at a depth of 1m for 0.5h.	No water penetration inside connector.	X	-						

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